



Material Content Data Sheet



Sales Product Name				XMC4500-E144F1024 AC		Issued		19. January 2018	
MA#				MA001619276					
Package				PG-LFBGA-144-10		Weight*		367.95 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	13.003	3.53	3.53	35341	35341	
wire	noble metal	palladium	7440-05-3	0.007	0.00		18		
	non noble metal	copper	7440-50-8	0.664	0.18	0.18	1804	1822	
encapsulation	organic material	carbon black	1333-86-4	0.374	0.10		1018		
	plastics	epoxy resin	-	25.834	7.02		70210		
substrate	inorganic material	silicondioxide	60676-86-0	160.992	43.76	50.88	437543	508771	
	inorganic material	Metal Hydroxide	-	2.532	0.69		6881		
	inorganic material	bariumsulfate	7727-43-7	3.977	1.08		10808		
	plastics	acrylic resin	-	4.602	1.25		12508		
	inorganic material	silicondioxide	60676-86-0	8.017	2.18		21789		
	plastics	epoxy resin	-	16.516	4.49		44887		
	inorganic material	glass fibre	-	17.722	4.82		48164		
plating	non noble metal	copper	7440-50-8	60.691	16.49	31.00	164946	309983	
	noble metal	gold	7440-57-5	0.198	0.05		537		
solderball	non noble metal	nickel	7440-02-0	0.541	0.15	0.20	1471	2008	
	noble metal	silver	7440-22-4	1.744	0.47		4739		
	non noble metal	tin	7440-31-5	48.079	13.07	13.54	130668	135407	
glue	plastics	epoxy resin	-	0.613	0.17		1667		
	noble metal	silver	7440-22-4	1.840	0.50	0.67	5001	6668	
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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